



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: N. KOYAMA et al  
Serial No.: 10/018,188  
Filed: December 18, 2001  
For: CMP ABRASIVE, METHOD FOR POLISHING  
SUBSTRATE AND METHOD FOR MANUFACTURING  
SEMICONDUCTOR DEVICE USING THE SAME, AND  
ADDITIVE FOR COMP ABRASIVE  
Group: 3724  
Examiner: T. ELEY

RECEIVED  
AUG 30 2004  
TECHNOLOGY CENTER 3700

PETITION FOR EXTENSION OF TIME

Commissioner For Patents  
POB 1450  
Alexandria, VA 22313-1450

August 25, 2004

Sir:

In the matter of the above-identified application, Applicants hereby respectfully petition for an extension of time to permit filing a response within the third month subsequent to expiration of the shortened statutory period set in the outstanding Office Action, mailed February 25, 2004. A credit card payment form in the amount of \$950.00 to cover the required fee for the requested extension of time is attached hereto.

It is respectfully requested that any shortage in the fee be charged to the deposit account of Antonelli, Terry, Stout & Kraus, LLP, Account No. 01-2135 (511.40998X00) and any excess fees credited to that account.

Respectfully submitted,  
**ANTONELLI, TERRY, STOUT & KRAUS, LLP**

William I. Solomon  
Registration No. 28,565

WIS/dks  
703-312-6600

08/26/2004 EABUBAK1 00000061 10018188

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